

# EDSFF Board Site Connector

## PCIe® Gen 5/Gen 6

Amphenol introduces the next-generation OverPass™ solution – EDSFF Board Site Connector. The 0.60mm pitch connector comes with a slim form factor design, capable of transmitting a high-speed signal up to PCIe® Gen 5 and PCIe® Gen 6 and allowing much greater signal path lengths while maintaining SI performance compared to conventional PCB routing methods.

The EDSFF cable solution not only provides an SI performance-ready signal transmission but also a new way of system design that is cost-effective, highly modular, scalable, and extremely easy to repair.

- High speed –PCIe® Gen 5/PCIe® Gen 6 capability
- Supports both cable and card edge connection



### FEATURES

- 0.60mm pitch, vertical configuration
- Up to PCIe® Gen 5, Gen 6 over 1.0 meter transmission distance
- Supports both cable applications
- Optional for three different mating heights

### BENEFITS

- Slim form factor for compact data center system designs
- Extends transmission range far more over the conventional PCB routes
- Provides flexibility in system design to meet highly modular, scalable and easy-to-repair requirements
- Saves system material cost, engineering and certification expenses with high succession of system design

## TECHNICAL INFORMATION

### MATERIAL

- Contact Base Metal: Copper Alloy
- Contact Area Finish: Gold over Nickel
- Solder Area Finish: Tin over Nickel
- Housing & Spacer: High temperature thermoplastic (UL 94V-0)
- Shorting Bar: Conductive Plastic
- Cage: Stainless Steel, Nickel plating overall

### MECHANICAL PERFORMANCE

- Durability: 250 mating cycles
- Mating Force: 0.6N/pin max.
- Unmating Force: 0.06N/pin min.

### SPECIFICATIONS

- Amphenol Product Specification: GH02V\*

### ELECTRICAL PERFORMANCE

- Contact Resistance: 30mΩ max. initial; 15mΩ max. change after test
- Dielectric Withstanding Voltage: 300VDC

### PACKAGING

- Tray

### APPROVALS AND CERTIFICATIONS

- UL

### ENVIRONMENTAL

- Humidity: EIA-364-31, Method III, Subject unmated specimens to 24 cycles between 25°C/ 80%RH and 65°C/ 50% RH
- Temperature Life: EIA-364-17, Method A Test Condition 2, Test Time Condition C, Subject mated specimens to 105°C for 168 hours
- Thermal Shock: EIA-364-32, Method A Test condition 1, -55°C to +85°C (10 cycles)

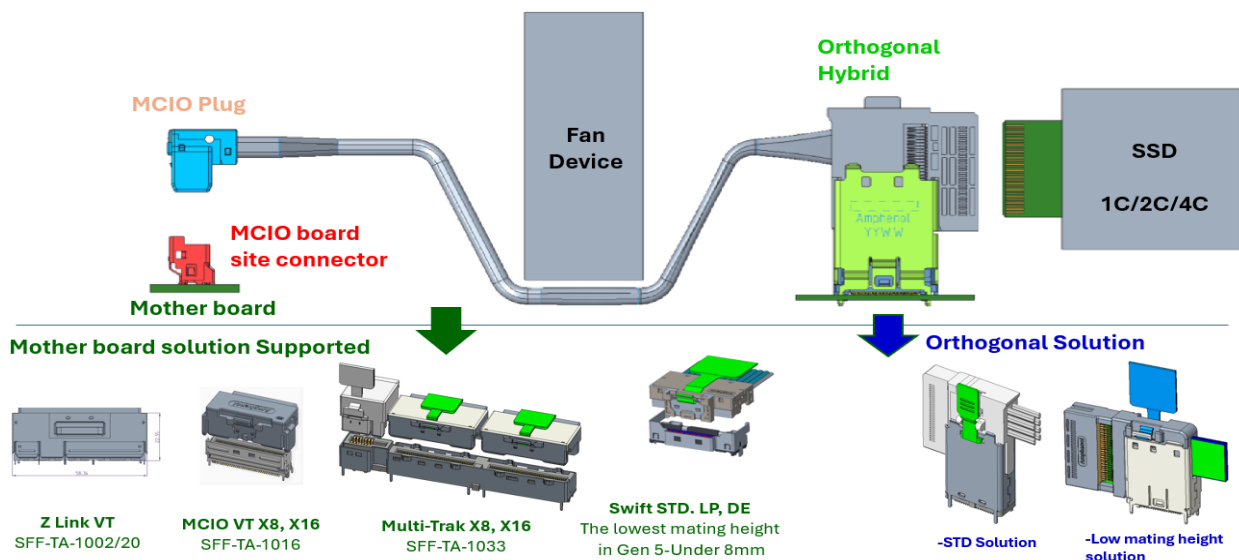
### TARGET MARKETS/APPLICATIONS



Baseband  
Commercial Systems  
Networking  
Radio Units

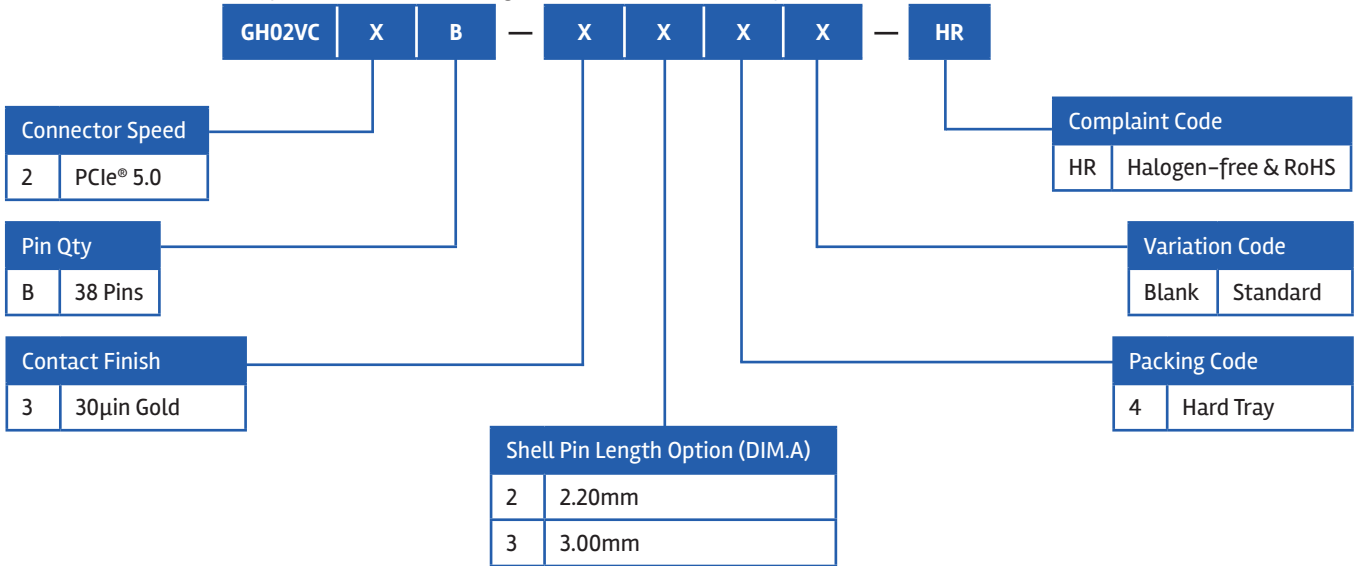


High-end Computing Systems  
Server and Storage Systems

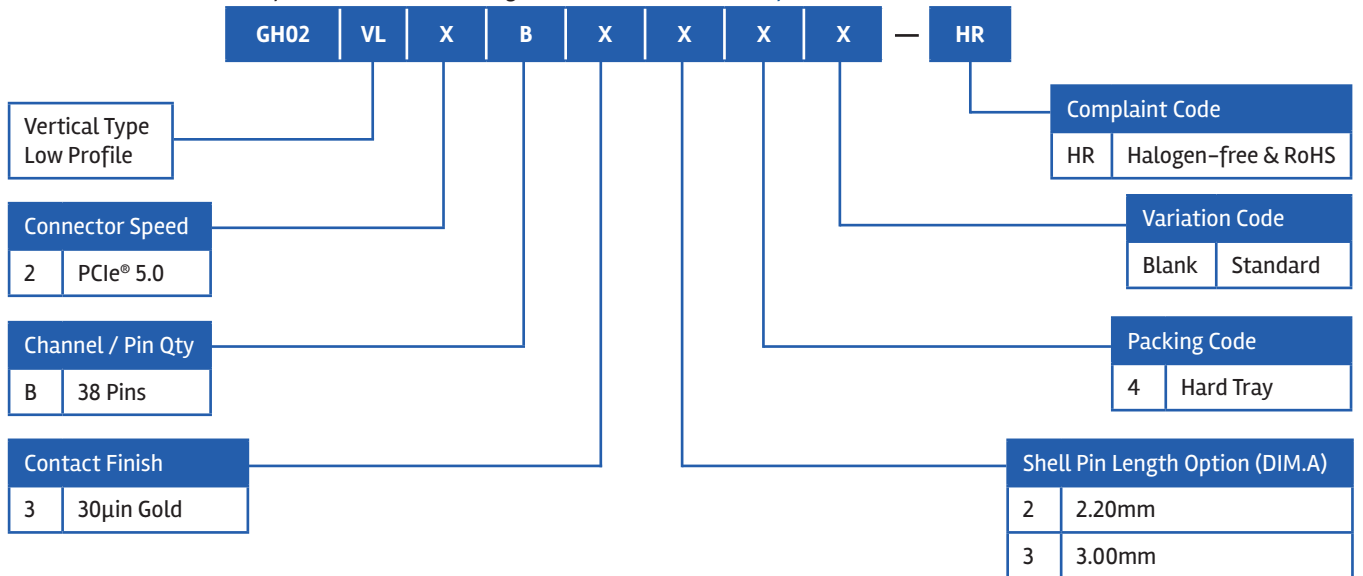


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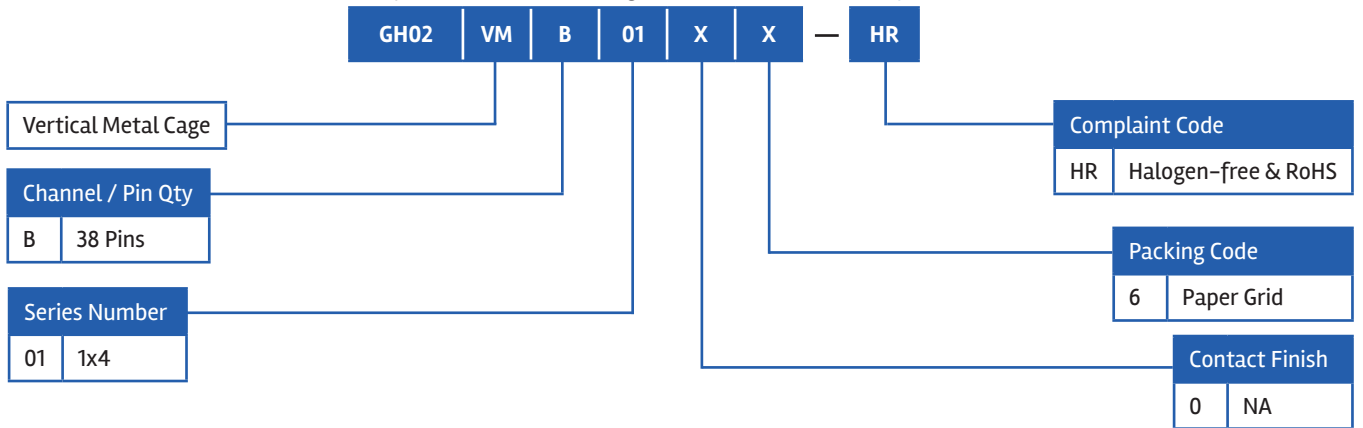


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